

2KBP005M THRU 2KBP10M SERIES

2.0 AMPERE MINIATURE SINGLE PHASE SILICON BRIDGE

FEATURES

- Glass passivated chip junctions
- Plastic material used carries Underwriters Laboratory flammability recognition 94V-0
- Ideal for printed circuit board
- Typical I_a less than .1 μ A
- Built-in printed circuit board stand-offs
- High case dielectric strength
- High temperature soldering guaranteed: 265°C/ 10 seconds at 5 lbs., (2.3kg) tension

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.
Positive or inductive load.

	2KBP005M	2KBP01M	2KBP02M	2KBP04M	2KBP06M	2KBP08M	2KBP10M	Units
Maximum Recurrent Peak Reverse Voltage	50	100	200	400	600	800	1000	V_{RRM}
Maximum RMS Bridge Input Voltage	35	70	140	280	420	560	700	V_{RMS}
Maximum DC Blocking Voltage	50	100	200	400	600	800	~1000	V_{DC}
Maximum Average Forward Rectified Output Current at $T_A = 50^\circ\text{C}$	2.0							A(AV)
Peak Forward Surge Current, single sine-wave superimposed on rated load (JEDEC Method)	60.0							Apk
If _t Rating for fusing ($t \leq 8.3\text{ms}$)	15.0							A ² s
Maximum Instantaneous Forward Voltage Drop per Bridge Element at 2.0A	1.1							Vpk
Typical Junction Capacitance per element (Note 1)	25.0							pF
Maximum Reverse DC Current Rated $T_A = 25^\circ\text{C}$	10.0							μ A
DC Blocking Voltage per element $T_A = 125^\circ\text{C}$	0.5							mA
Typical Thermal Resistance OJL (Note 2)	10.0							°C/W
Operating and Storage Temperature Range T_J, T_{STG}	-55 to +150							°C

NOTES

1. Measured at 1 MHz and applied reverse voltage of 4.0 volts.
2. Thermal Resistance from Junction to lead on P.C. Board Mounting per element.
3. Thermal Resistance from Junction to Ambient on P.C. Board Mounting: ROJA = 60°C/W for Full Wave Bridge Operation.

